

DUAL PNP SMALL SIGNAL SURFACE MOUNT TRANSISTOR

Case Material: Molded Plastic, "Green" Molding

Moisture Sensitivity: Level 1 per J-STD-020

Weight: 0.006 grams (approximate)

Compound. UL Flammability Classification Rating 94V-0

Terminals: Matte Tin Finish; Solderable per MIL-STD-202,

Mechanical DataCase: SOT363

Method 208

Features

- Ideally Suited for Automated Insertion
- For Switching and AF Amplifier Applications
- Ultra-Small Surface Mount Package
- "Lead-Free", RoHS Compliant (Note 1)
- "Green" Device (Note 2)
- Qualified to AEC-Q101 Standards for High Reliability

SOT363

Bottom View

Device Symbol

Pin-Out Top View

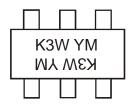
Ordering Information (Notes 3 & 4)

Product	Grade	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
BC857BS-7-F	Commercial	K3W	7	8	3,000
BC857BS-13-F	Commercial	K3W	13	8	10,000
BC857BSQ-7-F	Automotive	K3W	7	8	3,000

Notes:

- 1. No purposefully added lead.
- 2. Halogen and Antimony Free. Diodes Inc's "Green" policy can be found on our website at http://www.diodes.com
- 3. For packaging details, go to our website at http://www.diodes.com.
- 4. Products with Q-suffix are automotive grade. All other products are commercial grade.

Marking Information



K3W = Product Type Marking Code YM = Date Code Marking Y = Year (ex: X = 2010) M = Month (ex: 9 = September)

Date Code Key

Year	2010		2011	2012		2013	2014		2015	2016		2017
Code	X		Υ	Z		Α	В		С	D		E
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings @T_A = 25℃ unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	-50	V
Collector-Emitter Voltage	V _{CEO}	-45	V
Emitter-Base Voltage	V _{EBO}	-5.0	V
Collector Current	Ic	-100	mA
Peak Collector Current	I _{CM}	-200	mA
Peak Base Current	I _{BM}	-200	mA

Thermal Characteristics $@T_A = 25\%$ unless otherwise specified

Characteristic	Symbol	Value	Unit	
Power Dissipation (Note 5)	P_{D}	200	mW	
Thermal Resistance, Junction to Ambient Air (Note 5)	$R_{ hetaJA}$	625	°C/W	
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C	

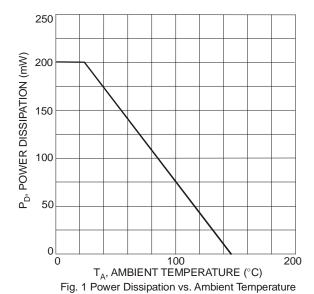
Electrical Characteristics @TA = 25°C unless otherwise specified

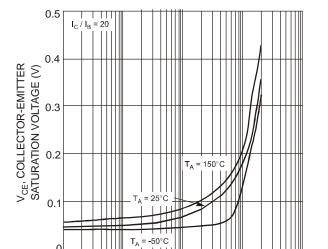
Characteristic (Note 6)	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV _{CBO}	-50		_	V	$I_C = 100 \mu A, I_B = 0$
Collector-Emitter Breakdown Voltage	BV _{CEO}	-45		_	V	$I_C = 10 \text{mA}, I_B = 0$
Emitter-Base Breakdown Voltage	BV _{EBO}	-5		_	V	$I_E = 100 \mu A$, $I_C = 0$
DC Current Gain	h _{FE}	220	1	475	_	$V_{CE} = -5.0V$, $I_{C} = -2.0$ mA
Collector-Emitter Saturation Voltage	V _{CE(sat)}	_	l	-100 -400	mV	$I_C = -10$ mA, $I_B = -0.5$ mA $I_C = -100$ mA, $I_B = -5.0$ mA
Base-Emitter Saturation Voltage	V _{BE(sat)}	_	-700	_	mV	$I_C = -10 \text{mA}, I_B = -0.5 \text{mA}$
Base-Emitter Voltage	V _{BE(on)}	-580	-665	-750	mV	$V_{CE} = -5.0V$, $I_{C} = -2.0mA$
Collector-Cutoff Current	Ісво	_		-15 -4.0	nΑ μΑ	V _{CB} = -30V V _{CB} = -30V, T _A = 150℃
Emitter Cutoff Current	I _{CEO}	_	_	-100	nA	$V_{EB} = -5.0V, I_{C} = 0$
Gain Bandwidth Product	f _T	100	_	_	MHz	$V_{CE} = -5.0V, I_{C} = -10mA,$ f = 100MHz
Collector-Base Capacitance	C _{CBO}	_		3	pF	$V_{CB} = -10V, f = 1.0MHz$
Emitter-Base Capacitance	C _{EBO}	_	11	_	pF	$V_{EB} = -0.5V, f = 1.0MHz$

Notes:

- 5. Device mounted on FR-4 PCB. Diodes Inc. suggested pad layout document can be found on our website at http://www.diodes.com 6. Short duration pulse test used to minimize self-heating effect.









10

100

1,000

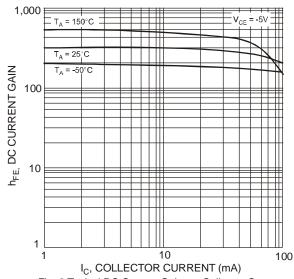


Fig. 2 Typical DC Current Gain vs. Collector Current

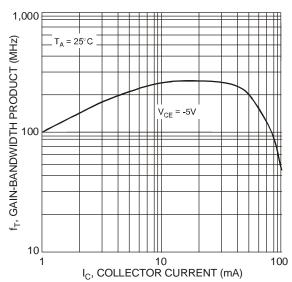
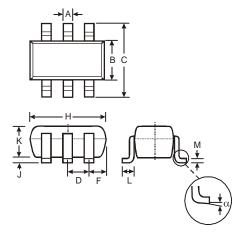


Fig. 4 Typical Gain-Bandwidth Product vs. Collector Current

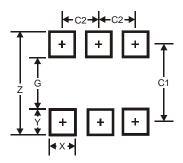
Package Outline Dimensions



SOT363					
Dim	Min	Max			
Α	0.10	0.30			
В	1.15	1.35			
С	2.00 2.20				
D	0.65 Typ				
F	0.40	0.45			
Н	1.80	2.20			
J	0	0.10			
K	0.90 1.00				
L	0.25	0.40			
М	0.10	0.22			
α	0°	8°			
All Dimensions in mm					



Suggested Pad Layout



Dimensions	Value (in mm)			
Z	2.5			
G	1.3			
X	0.42			
Υ	0.6			
C1	1.9			
C2	0.65			

IMPORTANT NOTICE

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

- A. Life support devices or systems are devices or systems which:
 - 1. are intended to implant into the body, or
 - 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
- B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2012, Diodes Incorporated

www.diodes.com